

APUESTAS DE TECNALIA en PRINTED ELECTRONICS

Cluster Functional Printing

Febrero 2021

INDICE

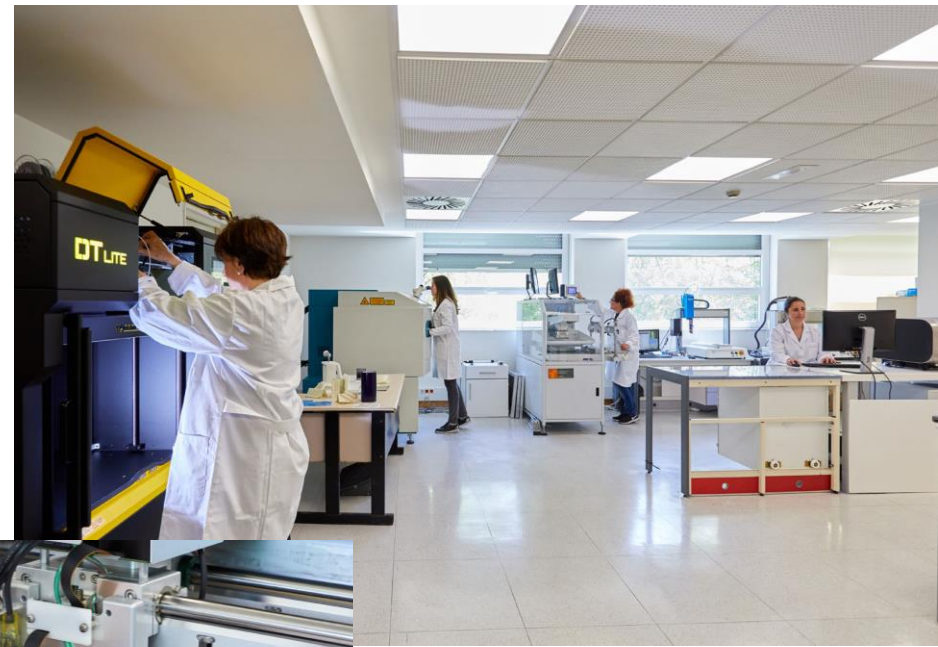
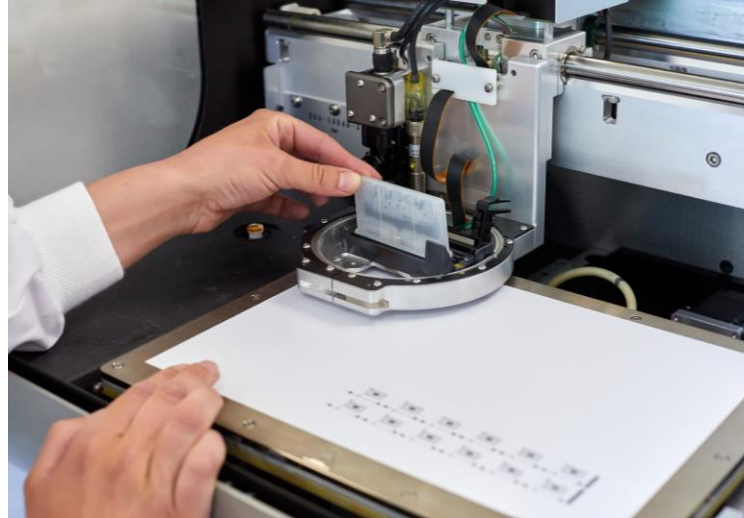
- ❑ Nuestra **propuesta de valor**
- ❑ **Retos** que abordamos



TECNALIA Y LA IMPRESIÓN FUNCIONAL

PROPUESTA DE VALOR

Desde la idea hasta el prototipo de producto. Pasando por el diseño, selección y formulación de materiales (sustrato y aportes), desarrollo de proceso de impresión y caracterización / validación funcional.



TECNICAS de IMPRESION

- Screen-printing: AUREL Automation model 900
- Ink-jet printing: Dimatix DMP2831
- Dispensing: Solenoid valve and rotary valve Nordson Ultimius
- Aerosol-jet: Neotech JP15X
- Nanojet: Neotech JP15X
- Piezojet: Neotech JP15X
- Lithographic techniques (EVG620): photolithography; microcontact printing, UV-NIL and Thermal-NIL
- Curing: Laser (Rofin 100W), UV, Forming, UV-LED (Phoseon)



RETOS QUE ABORDAMOS

- IMPRESIÓN DIRECTA SOBRE PIEZA 3D
- EMBEBER EN COMPOSITES
- IMPRIMIR SOBRE SUSTRATOS NO CONVENCIONALES
- IMPRIMIR FUNCIONES



INK-3D

Direct 3D Printing based technol
conductive/dielectric inks on 3D
manufacturing processes such as



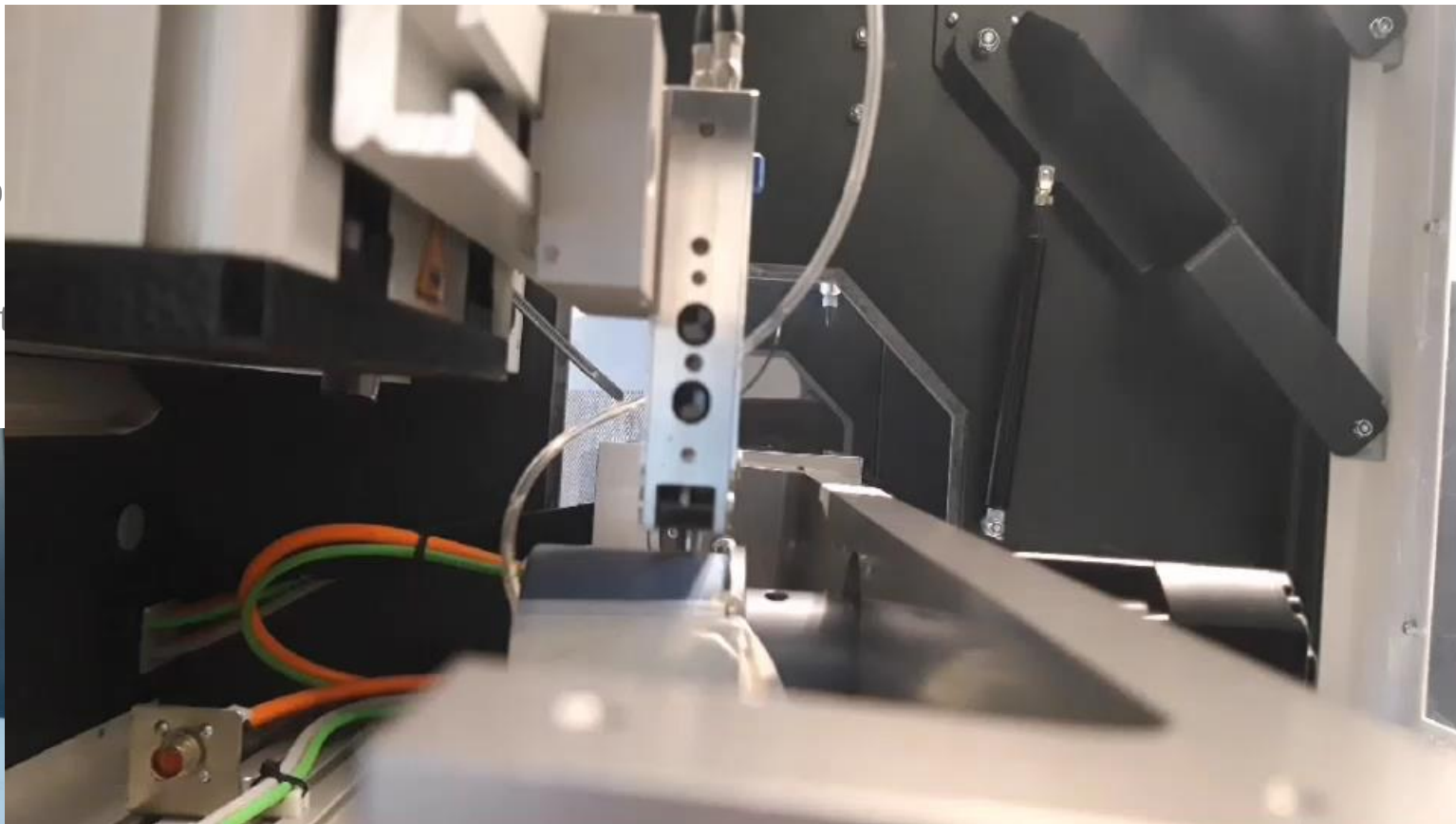
Application number

File No. to be used for
priority declarations

Date of receipt

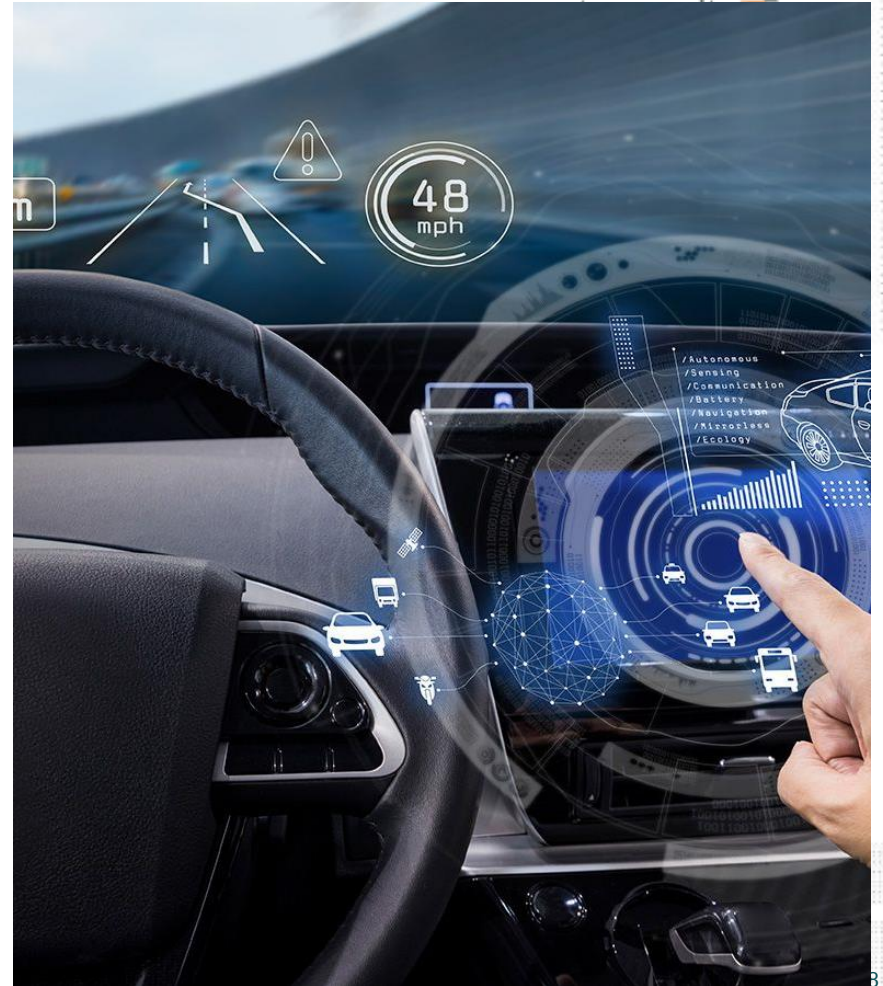
IMPRIMIR DI

- Microdisp
- PiezoJet/
- Aerosoljet



RETOS QUE ABORDAMOS

- IMPRESIÓN 3D
- EMBEBER EN COMPOSITES
- IMPRIMIR SOBRE DIVERSOS SUSTRATOS
- IMPRIMIR FUNCIONES



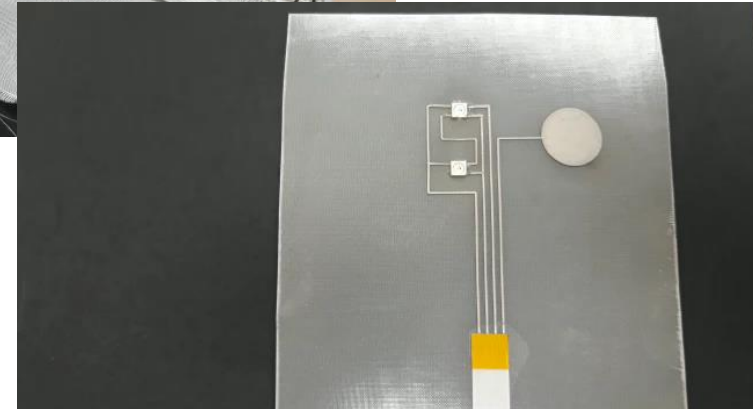
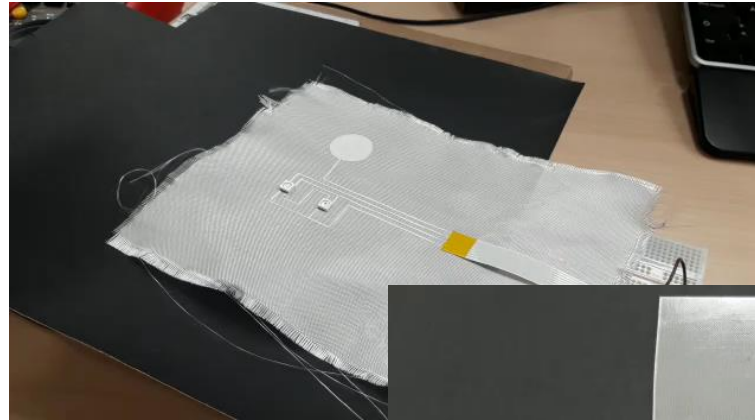
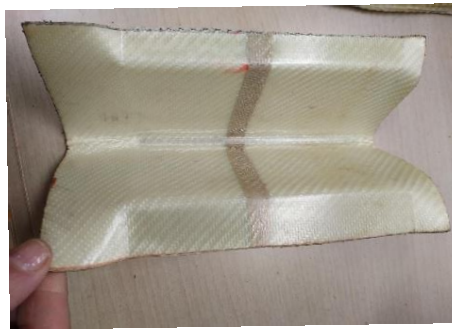
EMBEBER EN COMPOSITES

Imprimimos sobre:

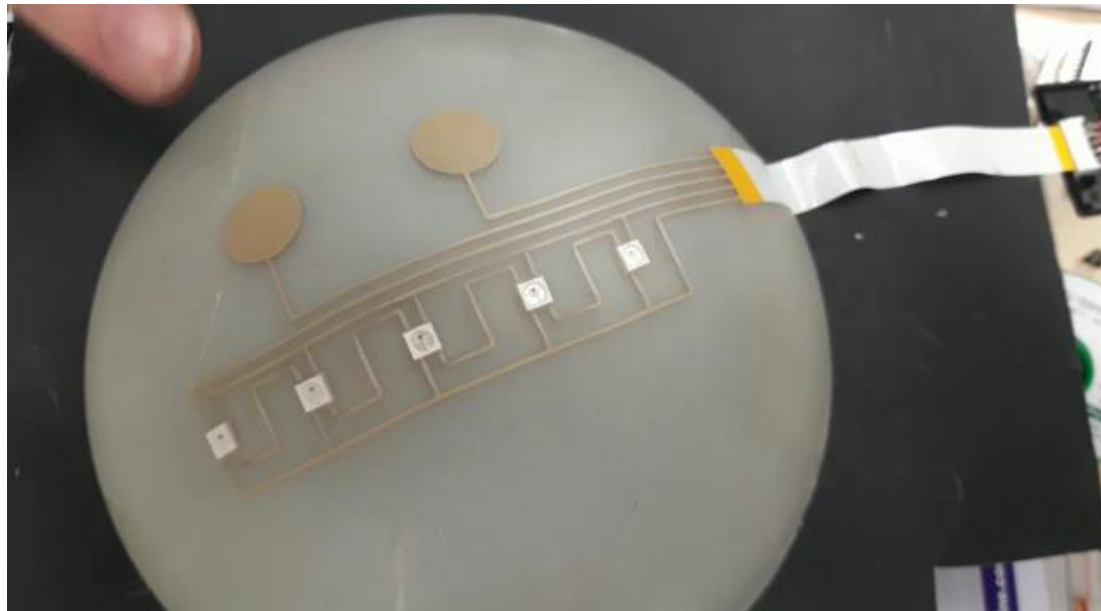
- Tejidos secos no-conductores

Y luego

- Polimerización in situ con tejido impreso
- Proceso de infusión, RTM, etc.. Con distintas resinas: epoxi, fenólica, etc..



SCOMP



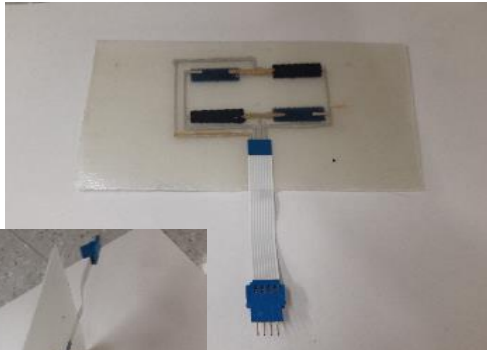
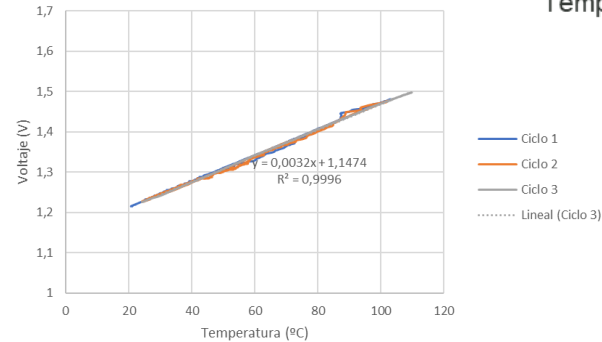
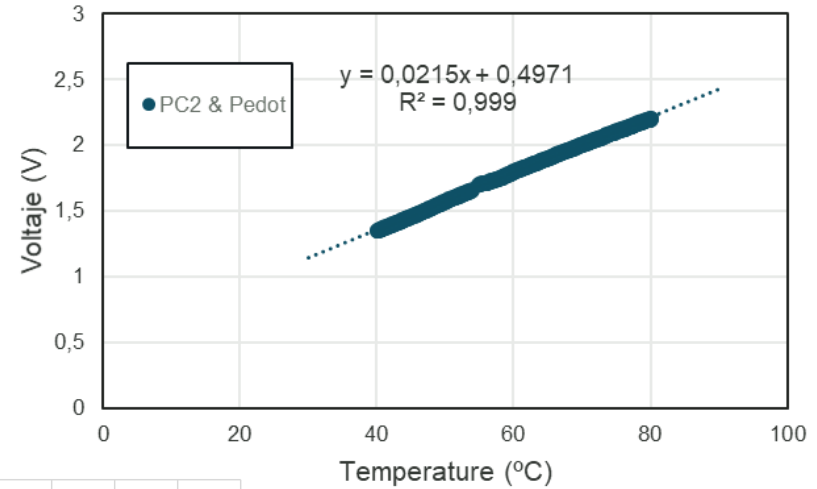
Application number	EP 20382664.3
File No. to be used for priority declarations	EP20382664
Date of receipt	24 July 2020

Method for manufacturing polymer composites with embedded functionalities

Composite part with leds, touch buttons and electric circuits

Temperature sensors in Wheatstone bridge configuration

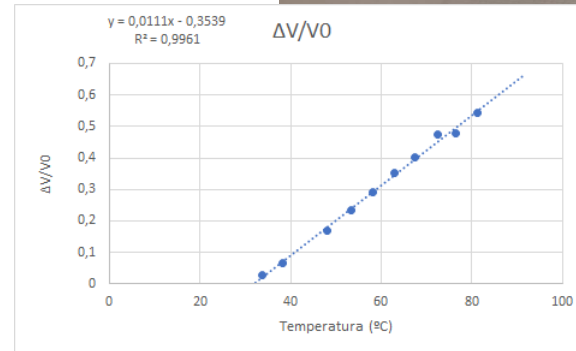
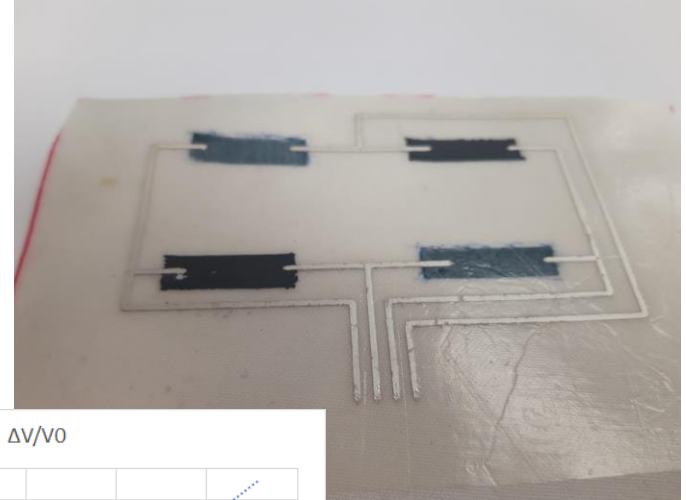
Inks used: Ag paste, Carbon paste, PEDOT



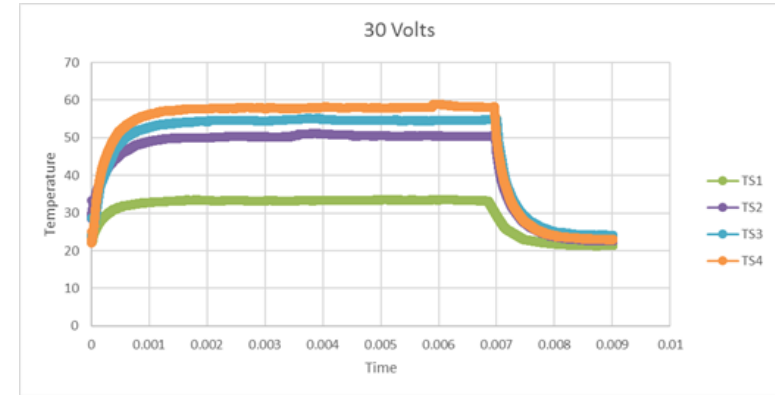
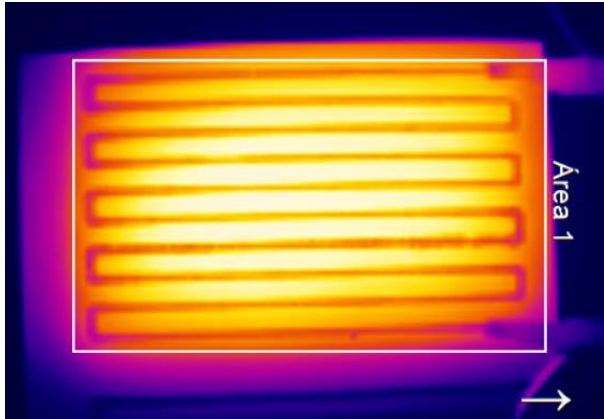
Inks used: Ag, Carbon based, PEDOT

Tested for Structural Health Monitoring (SHM)
in composites as no delamination is introduced

- GF up to 30



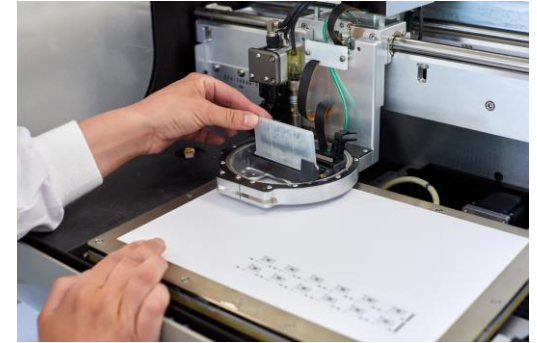
Inks used: Ag paste, Carbon paste



SELF-LIMITING THERMAL BEHAVIOUR OF CARBON PASTES. Temperature increases until a stabilized temperature determined by the voltage applied and the resistance of the lines.

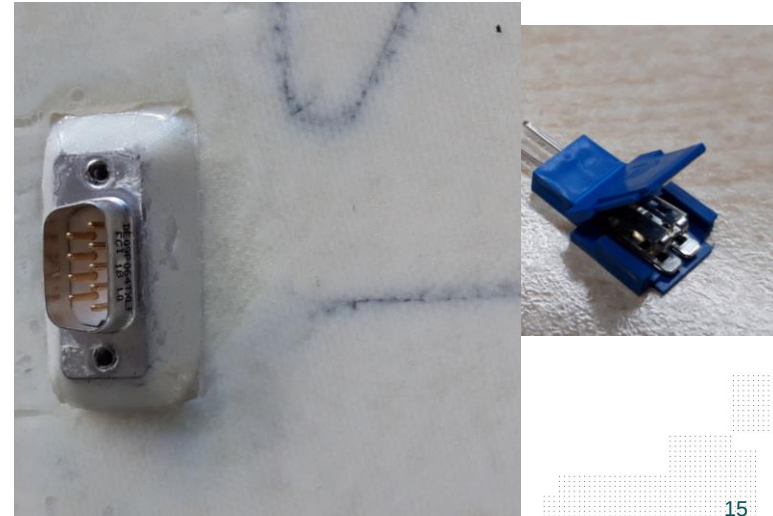
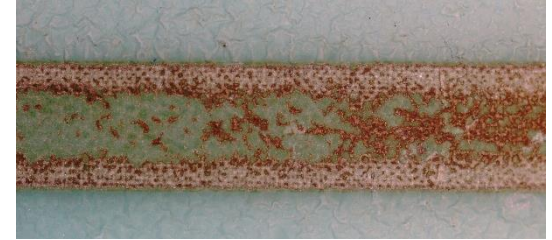
ANTENAS FLEXIBLES

- Sustratos: TYVEK; papel; PET, nomex
- Técnicas de deposición empleadas: Ink-jet o micro-dispensación.
- Tintas de Ag, grafeno



OTROS RETOS PARA OBTENER PROTOTIPOS

- Benchmarking **encapsulantes** para aislamiento dieléctrico, frente a diversas condiciones ambientales (ensayos en cámara climática, choques, etc..)
- Benchmarking **conectorización** (ensayos de robustez)
- Benchmarking de **tecnologías de unión conductoras** (ensayos de unión)
- Benchmarking **sistemas de alimentación flexibles o miniaturizados**



ESKERRIK ASKO
GRACIAS
THANK YOU
MERCI

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